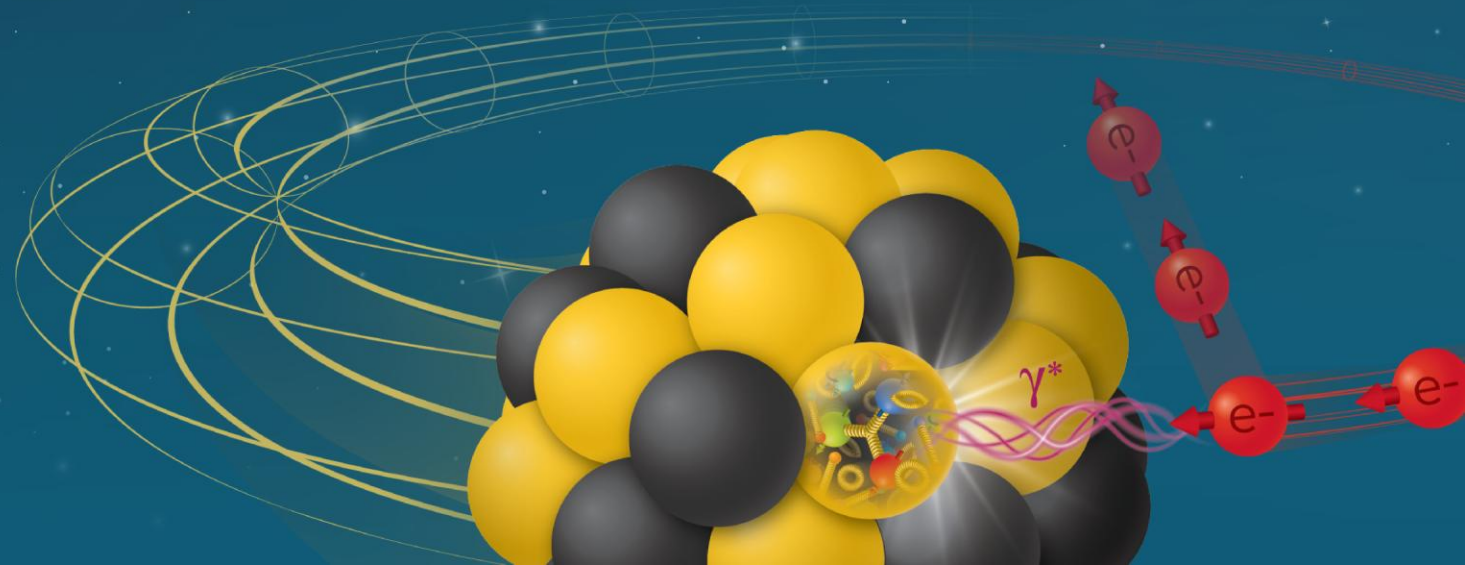


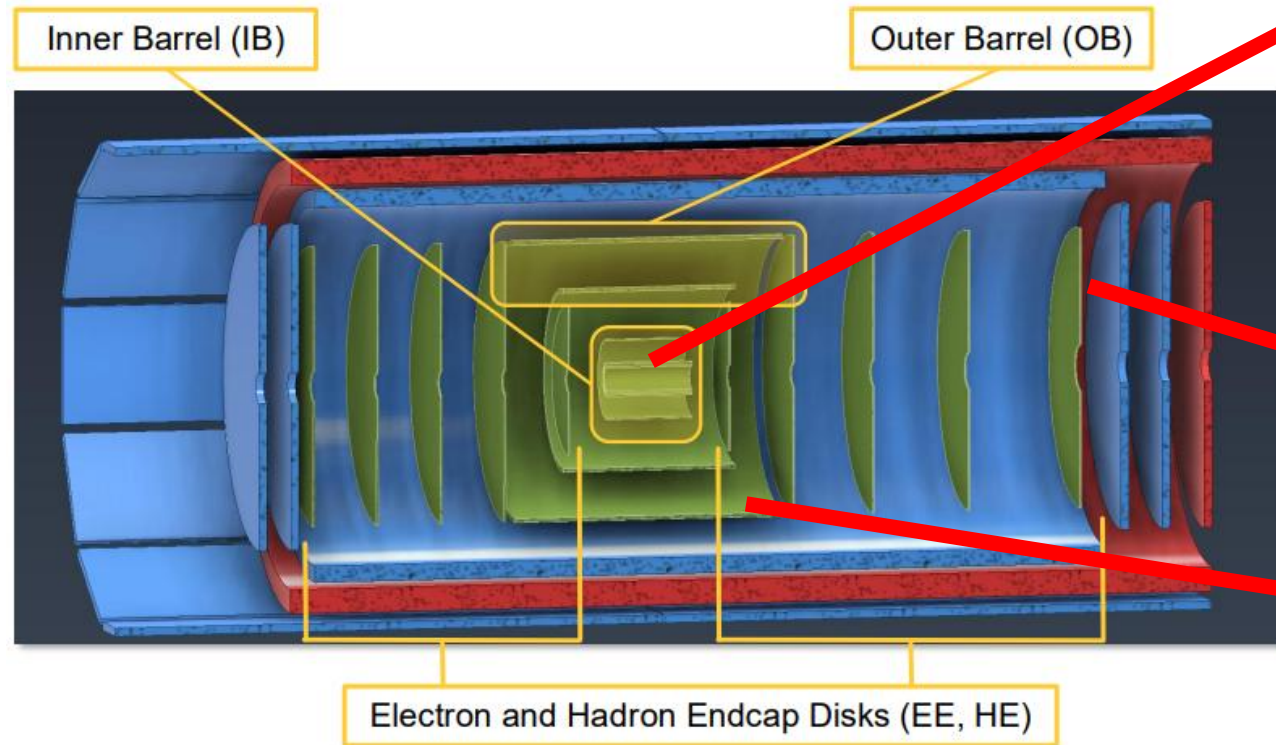
Outer Barrel System



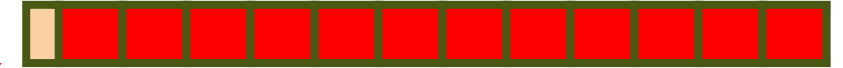
Electron-Ion Collider

Introduction

SVT Silicon Scheme



Inner Barrel



- Thinned silicon bent around beampipe
- Use wafer-scale MOSAIX from ITS3

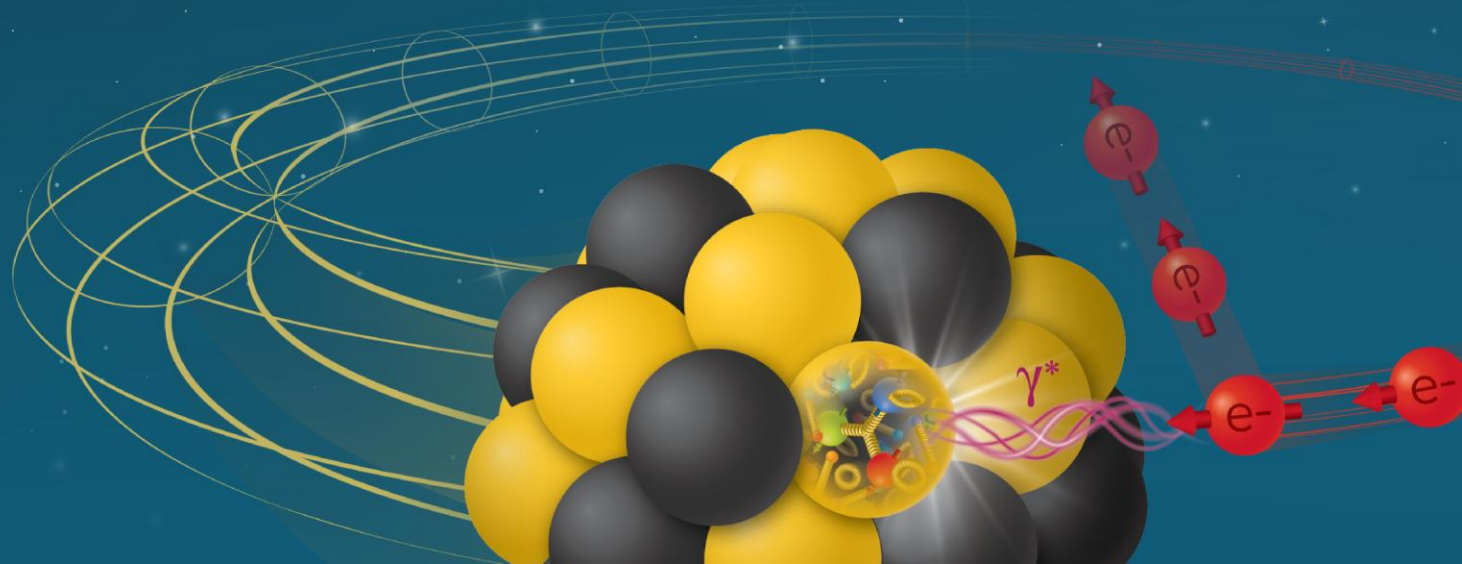
Outer Barrel and Discs



- Smaller Version of MOSAIX with minimum necessary changes (EIC-LAS)
- Supporting AncASIC

AncASIC and LAS

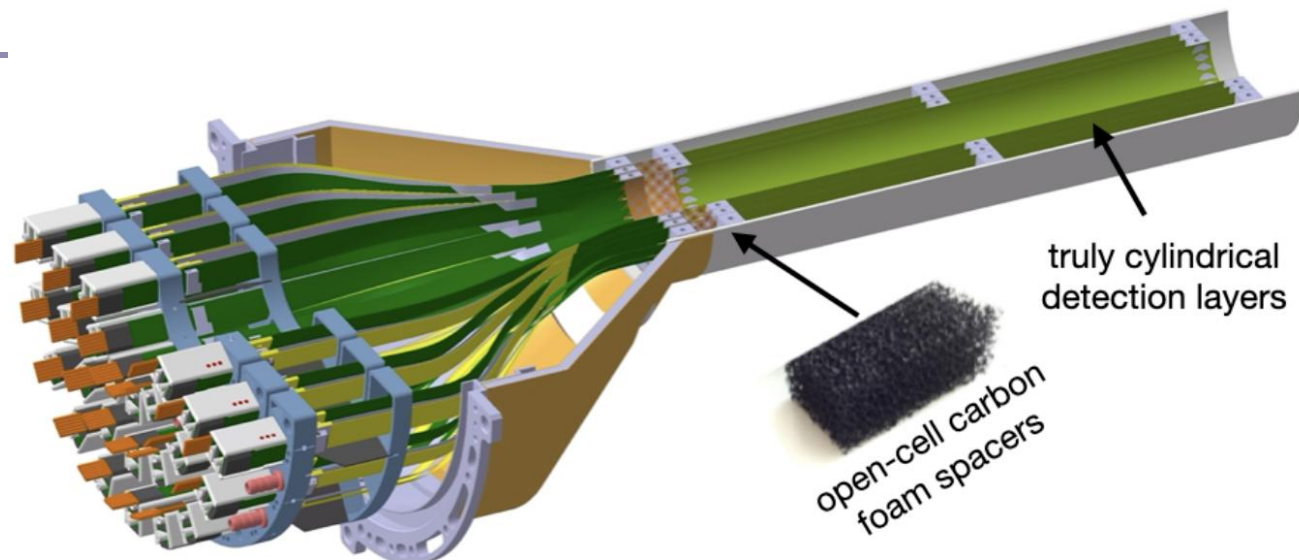
Electron-Ion Collider



Ancillary ASIC

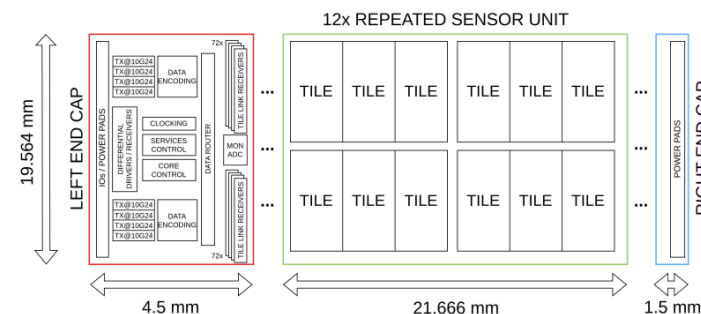
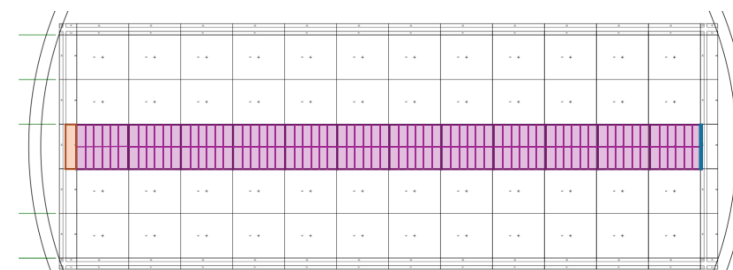
Why AncASIC?

- Some MOSAIX/LAS features require adaptation to stave/disc operation:
 - Point-to-point slow control
 - Point-to-point powering
 - Precise negative back bias
- May be technically unfeasible to integrate these features in the LAS
- Limited prototyping
- MOSAIX schedule is an external dependency
- For these reasons, develop supporting ASIC instead



<https://ep-news.web.cern.ch/content/alice-its3-clears-major-milestone>

MOSAIX



Ancillary ASIC

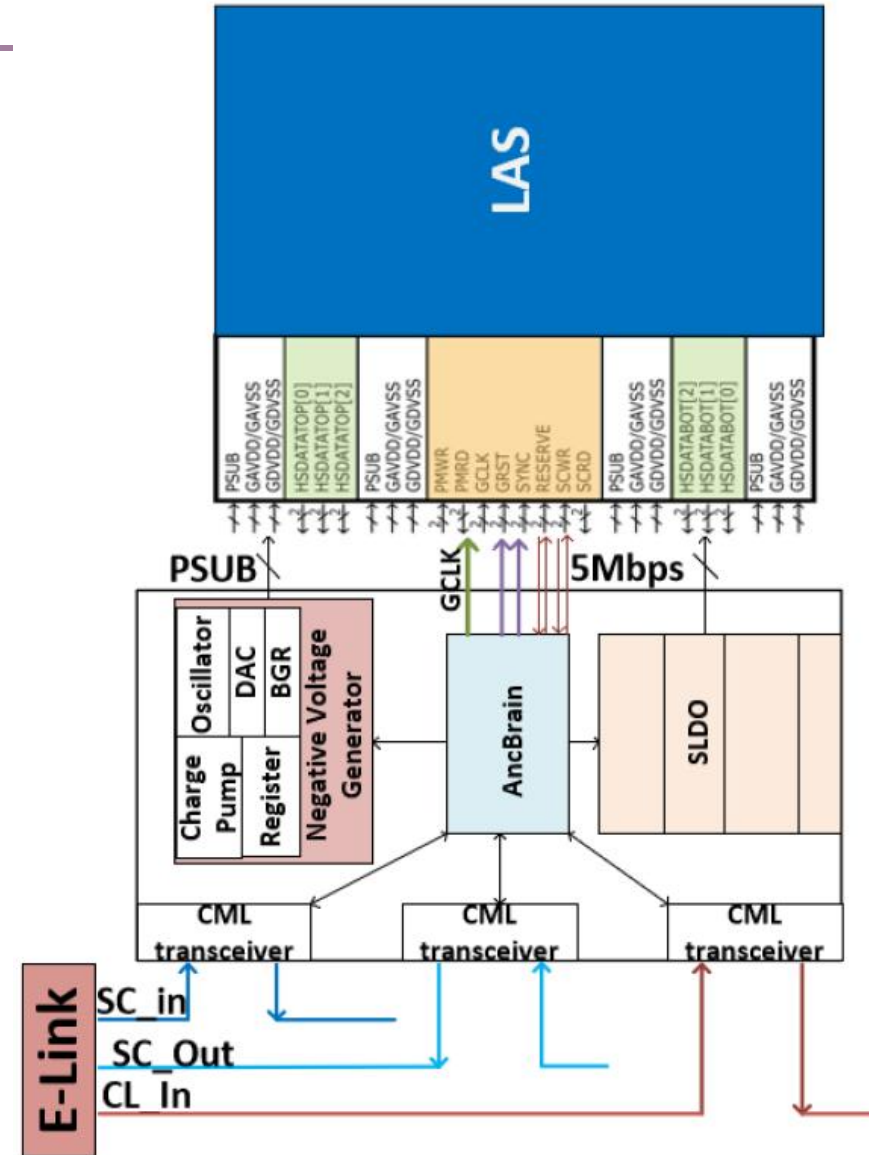
Why AncASIC?

- Some MOSAIX/LAS features require adaptation to stave/disc operation:
 - Point-to-point slow control → Serialised Slow Control interface from EIC-LAS to IpGBT
 - Point-to-point powering → SLDO for serial powering
 - Precise negative sensor bias → Local Negative Voltage Generator
 - May be technically unfeasible to integrate these features in the LAS
 - Limited prototyping
 - MOSAIX schedule is an external dependency
 - For these reasons, develop supporting ASIC instead
- Develop independent supporting chip
 - Development decoupled from MOSAIX availability
 - No modification of MOSAIX needed
 - 110nm XFAB process
 - 4 MPW runs a year
 - Cost effective

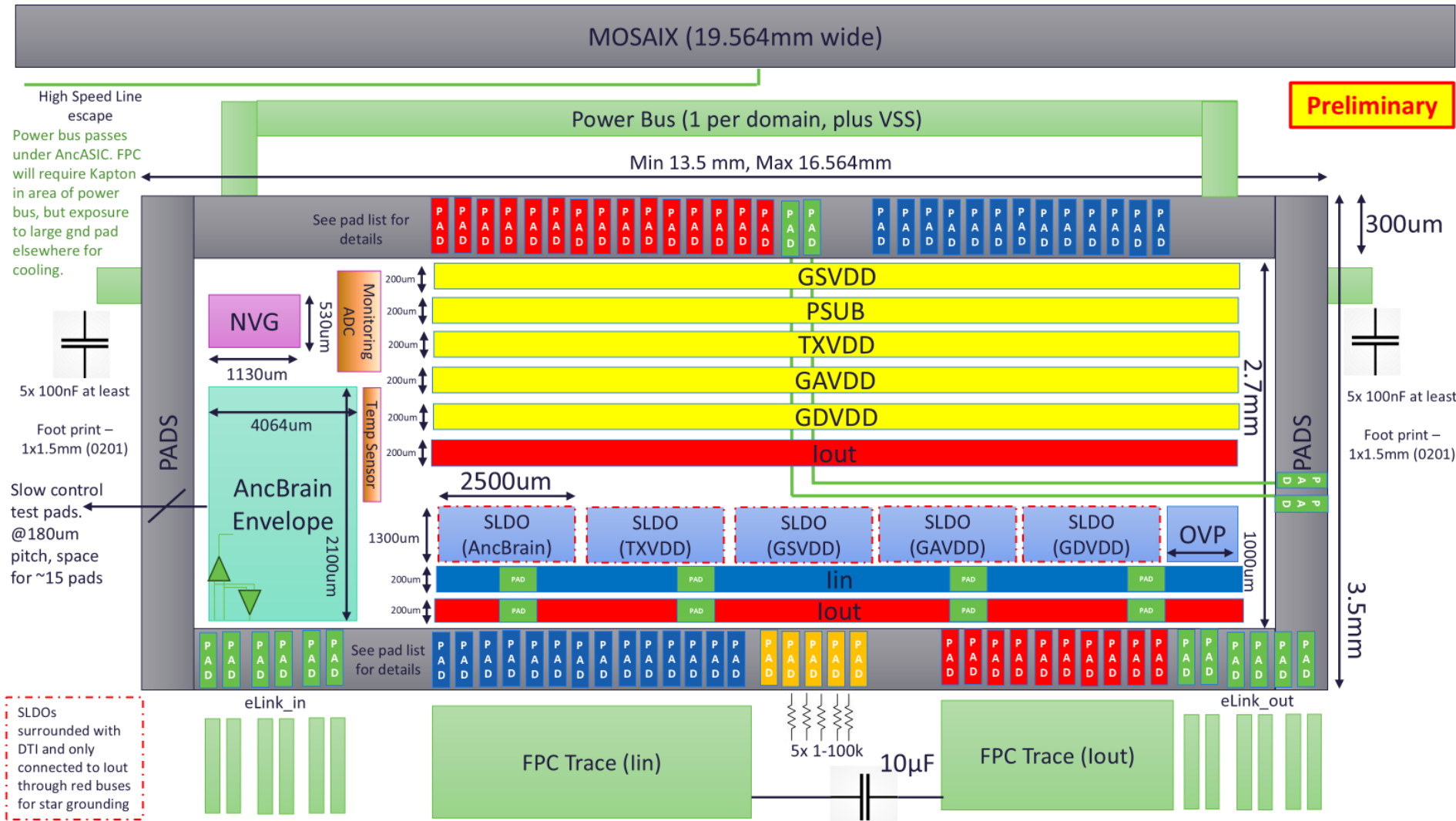
Ancillary ASIC

Why AncASIC?

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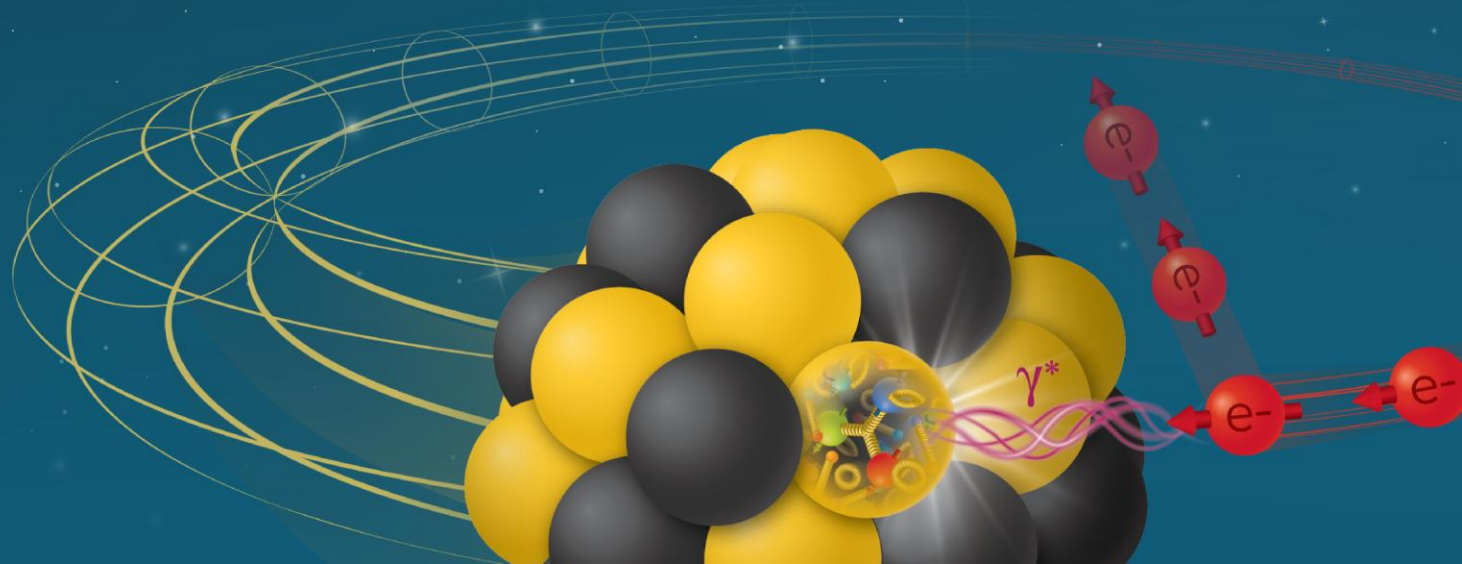
AncASIC - Updated Plan



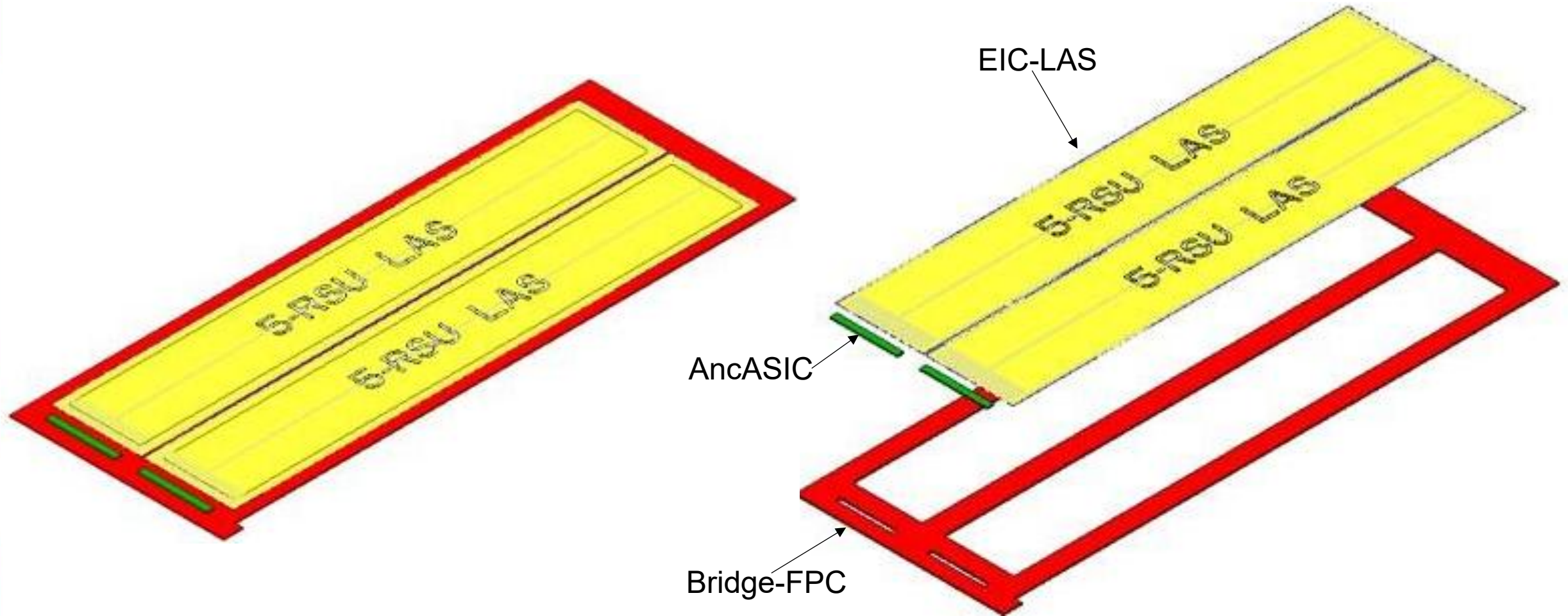
Still being developed...

FPC

Electron-Ion Collider



OB Module on Bridge-FPC

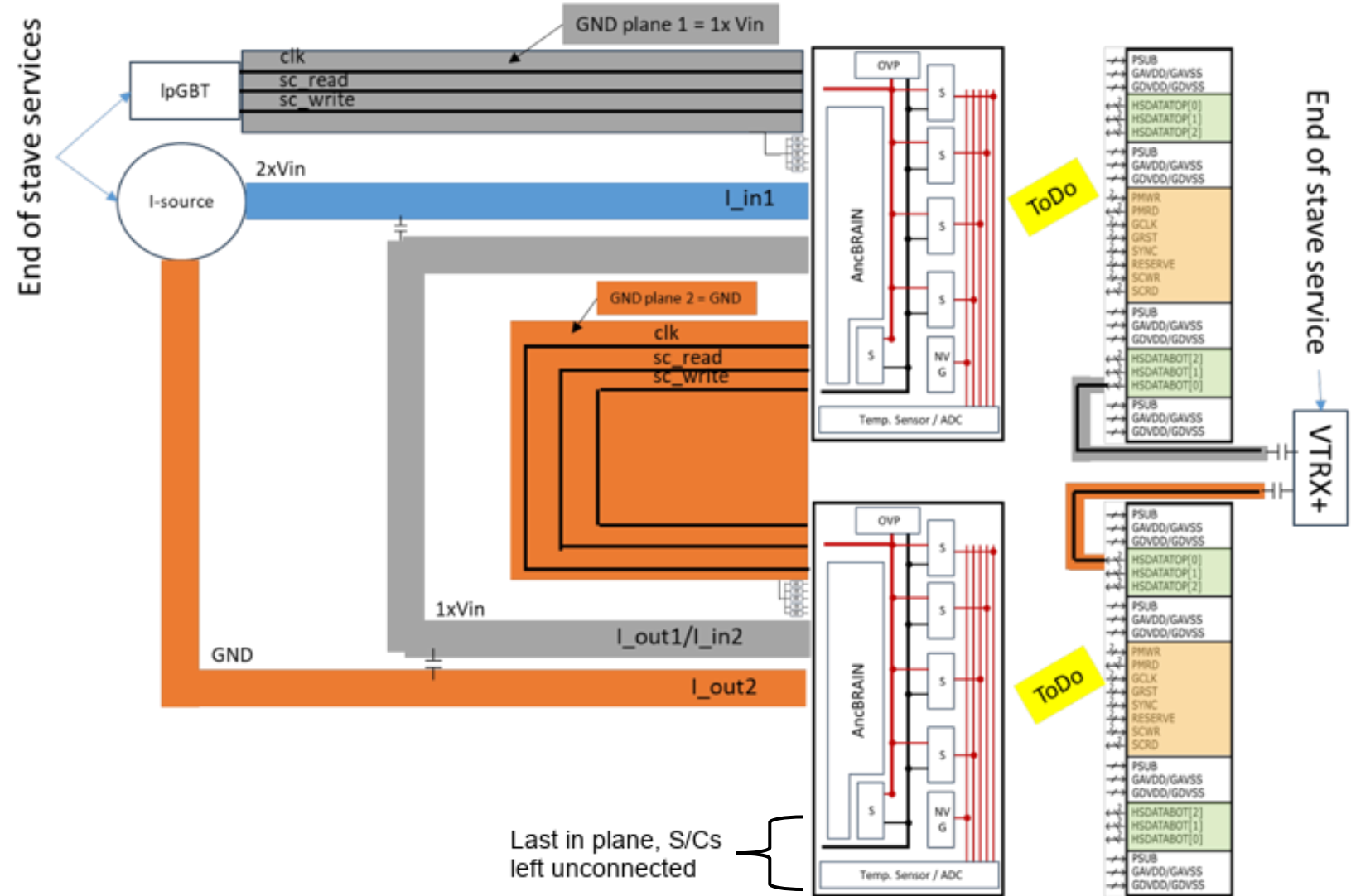


OB Module Connections

Topological sketch

$I_{in} = \text{const}$

clk, sc_read, sc_write:
AC or DC coupled?

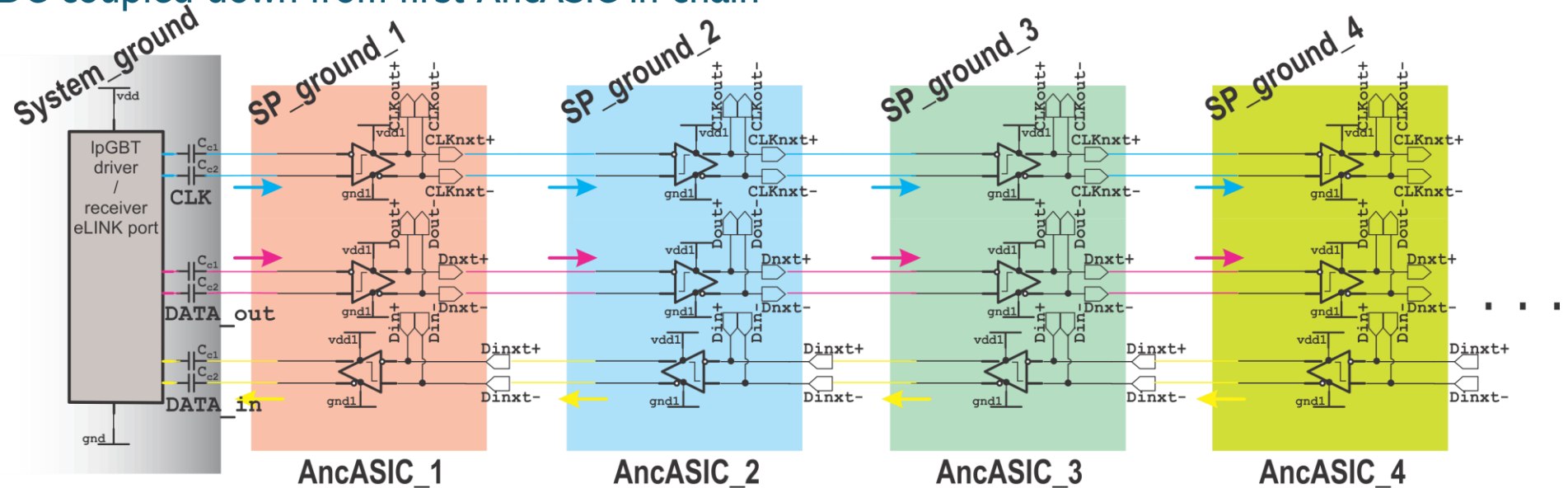


From and To AncBrain

Summary (ePortTX.pptx / ePortRx.pptx)

Main questions:

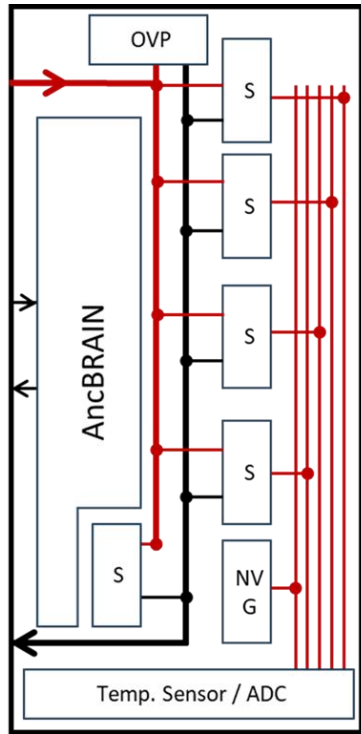
- (2) where AC and DC coupling should be used and how wired to EPort Group / eLinks ?
 - Proposal:
 - AC-coupled only to IpGBT (up-link and down-link), with coupling capacitors next to IpGBT
 - DC-coupled down from first AncASIC in chain



Advantages:

- Best for long chain of AncASICs,
- All but first AncASIC can entirely stop transmission

Grounding: AncAsic – LAS

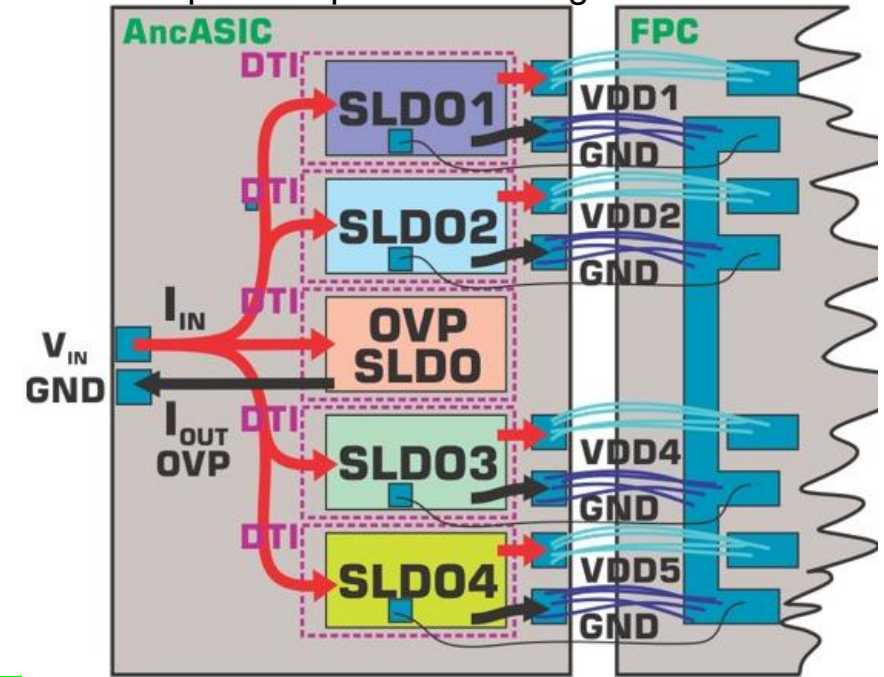


- GSVDD/GSVSS
- GAVDD/GAVSS
- GDVDD/GDVSS
- TXVDD/TXVSS
- PSUB
- HS DATA
- CTRL,CLK, ETC

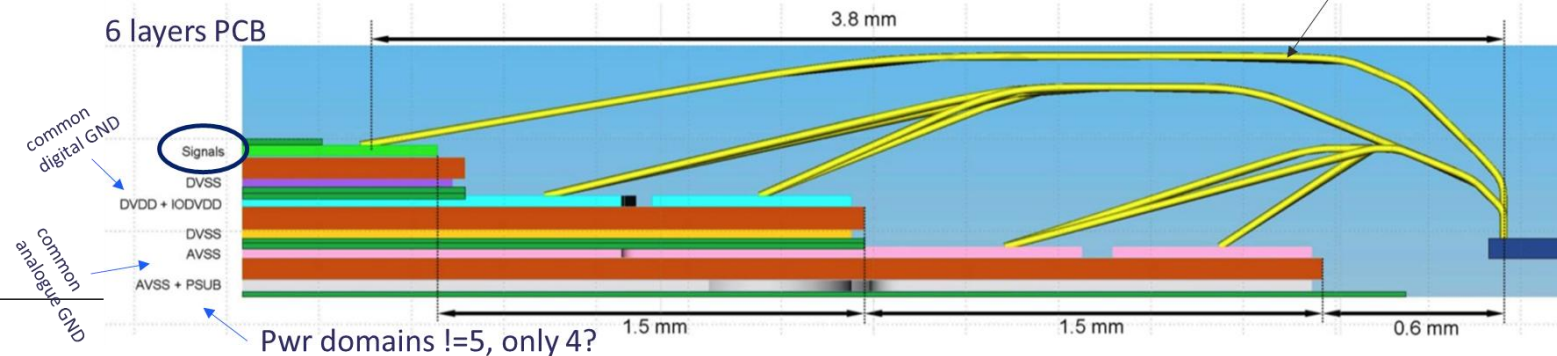


Common gnd? **Yes?**
 Or common analogue gnd
 and common digital gnd? **No?**

G.Deptuch <https://indico.bnl.gov/event/30317/>

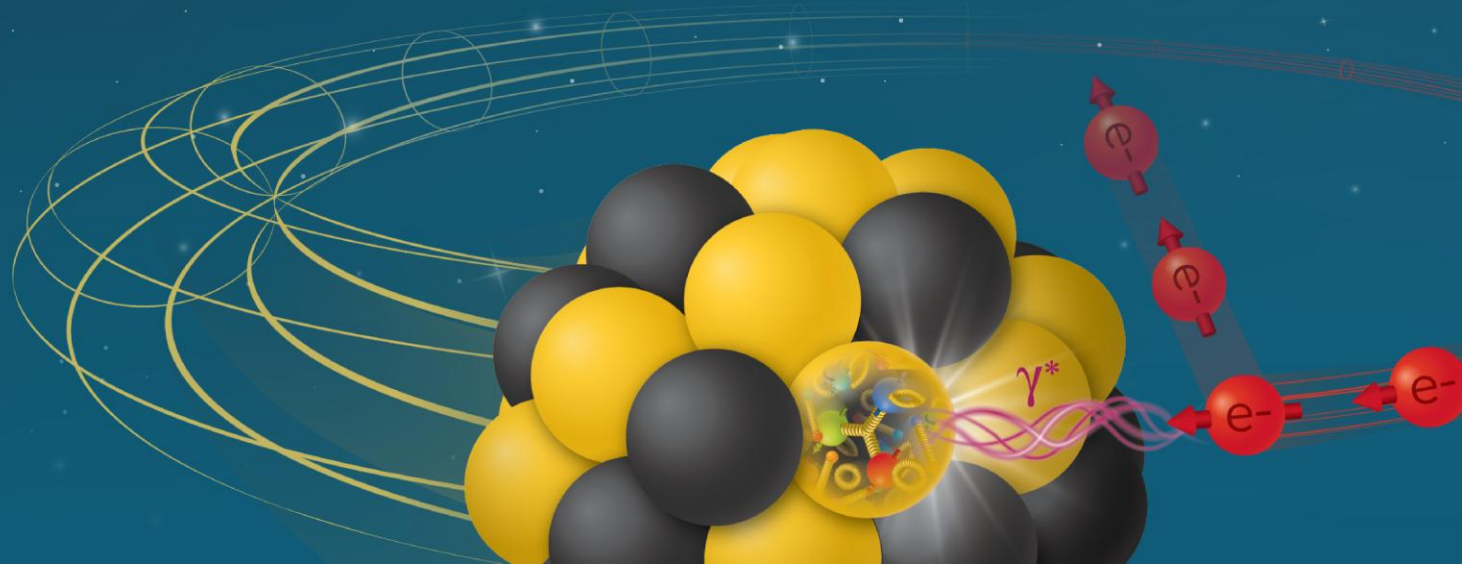


MOSAIX (From ITS3 TDR)

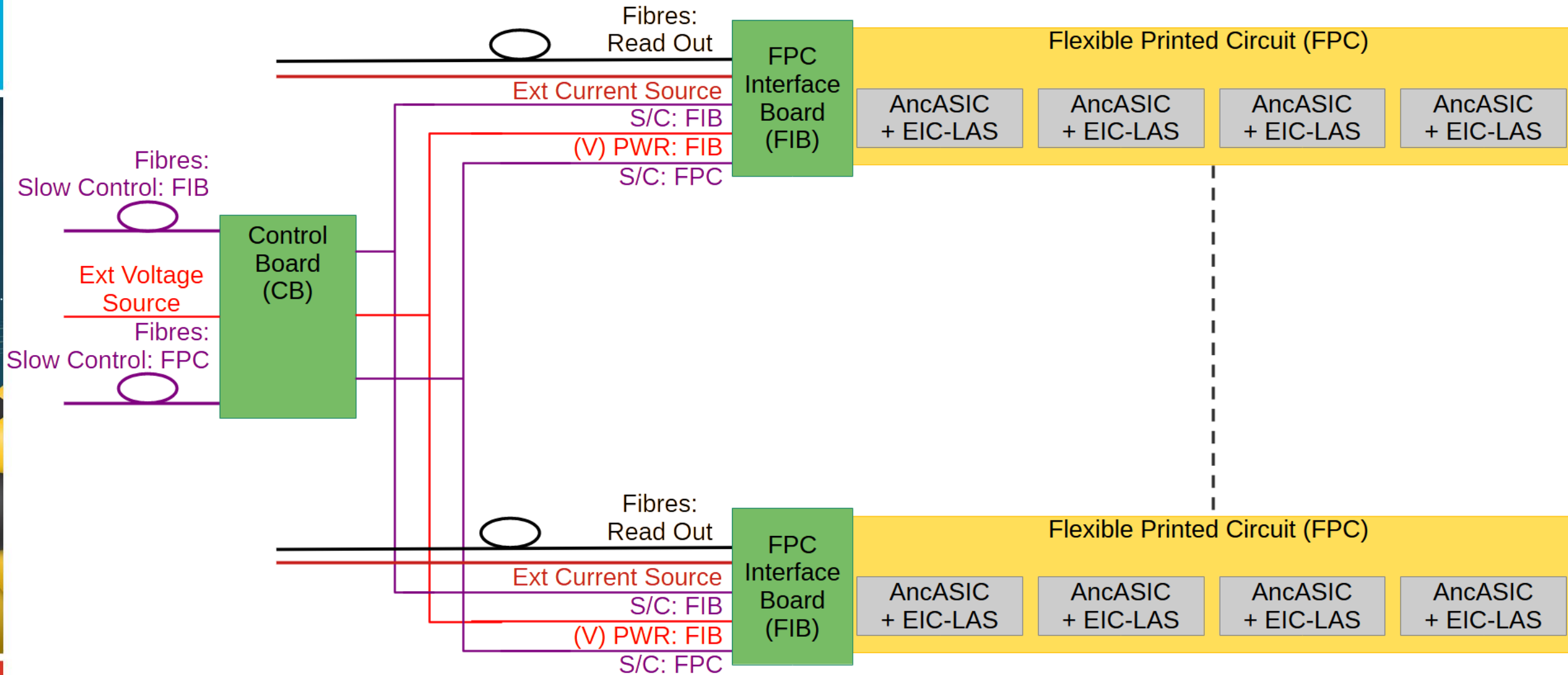


Beyond the FPC...

Electron-Ion Collider



Basic OB/Disk architecture



Beyond the CB and FIBs

- All connections exiting the SVT volume go via a patch panel (PP).
 - e-side and h-side PP used on all staves.
- From the PPs:
 - FIB power connects to current sources (1 channel per L3 FIB, 2 channels per L4 FIB).
 - FIB fibres (HS data) connect to a data aggregator board. Prior to being received at the control room.
 - CB power connects to voltage sources (1+ CB per channel).
 - CB fibres (S/Cs) connect to an aggregator board.